



8041-1018

PATENTS

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of

Manabu MIZUSAKI

Confirmation No. 7669

Serial No. 09/847,370

Group 2827

Filed May 3, 2001

ELECTRODE STRUCTURE OF A CARRIER
SUBSTRATE OF A SEMICONDUCTOR DEVICE

RECEIVED
U.S. MAIL ROOM
MAR 12 2003

INFORMATION DISCLOSURE STATEMENT

Commissioner for Patents

Washington, D.C. 20231

Sir:

In compliance with Rules 1.97 and 1.98, and in fulfillment of the duty of disclosure under Rule 1.56, the accompanying documents, copies of which are attached to this statement, are made of record on the enclosed sheet.

A concise explanation of the relevance of these items is that these references were cited by the Japanese Patent Office in the corresponding Japanese Application Serial No. 2000-140174, filed May 12, 2000. A copy of the Japanese Official Action in which they were cited is attached hereto, with what is believed to be the pertinent portion enclosed in a wavy line. An English translation of the enclosed portion is also attached hereto.

Under the provisions of 37 CFR 1.97(e), the undersigned hereby certifies that each item of information contained in this Information Disclosure Statement was first cited in any communication from a foreign Patent Office in a

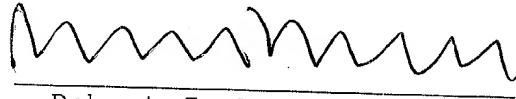
S.N. 09/847,370

counterpart foreign application not more than three months prior to the filing of this Statement.

Respectfully submitted,

YOUNG & THOMPSON

By



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整理番号 53209355

発送番号 410592

発送日 平成14年12月11日

1 / 2

拒絶理由通知書

特許出願の番号

特願2000-140174

起案日

平成14年12月 2日

特許庁審査官

坂本 薫昭

9265 4R00

特許出願人代理人

金田 暢之 (外 2名) 様

適用条文

第29条第2項

この出願は、次の理由によって拒絶をすべきものである。これについて意見があれば、この通知書の発送の日から60日以内に意見書を提出して下さい。

理由

この出願の下記の請求項に係る発明は、その出願前日本国内又は外国において頒布された下記の刊行物に記載された発明に基いて、その出願前にその発明の属する技術の分野における通常の知識を有する者が容易に発明をすることができたものであるから、特許法第29条第2項の規定により特許を受けることができない。

記 (引用文献等については引用文献等一覧参照)

- ・請求項 1～7
- ・引用文献等 1～3
- ・備考

電極の中央領域に凹部が形成され、空気抜きのスリットを有する電極を備えたキャリア基板は引用例1に記載されている。そして、スリットの形状は設計事項にすぎない。また、電極を円筒状とするものは引用例2, 3に記載されるように周知である。

引用文献等一覧

1. 特開平11-330294号公報
2. 特開平9-64231号公報
3. 特開平5-62980号公報

先行技術文献調査結果の記録

- ・調査した技術分野 I P C 第7版
- HO1L 23/12

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2 / 2

この先行技術文献調査の記録は、拒絶理由を構成するものではない。

この拒絶理由通知書の内容に関する問い合わせ先

特許審査第三部 電子素材加工 審査官 坂本薰昭

電話 03-3581-1101 内線 6362

MIZUSAKA-U.S. Pat. Appl. 09/847,370
Ref. NEC2410-US

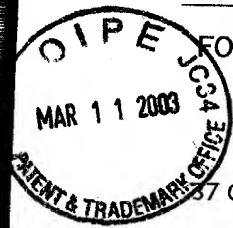
Claims 1-7
Citations 1-3

Remarks:

In Citation 1, reference is made to a carrier substrate provided with an air extraction slit and in which an indentation is formed in the center region of an electrode. Also, the shape of the slit is nothing more than a matter of design. In addition, making the electrode to be cylindrical in shape is already known from such as Citations 2 and 3.

Reference Citation List

1. Japanese Laid Open Patent Publication Hei 11-330294
2. Japanese Laid Open Patent Publication Hei 9-64231
3. Japanese Laid Open Patent Publication Hei 5-62980



FORM PTO-1449

U.S. DEPARTMENT OF COMMERCE
PATENT AND TRADEMARK OFFICEINFORMATION DISCLOSURE
STATEMENT BY APPLICANT

(Use several sheets if necessary)

37 CFR 1.98(b)

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U.S. PATENT DOCUMENTS

EXAMINER INITIAL	PATENT NUMBER	ISSUE DATE	PATENTEE	CLASS	SUB CLASS	FILING DATE IF APPROPRIATE
AA						
AB						
AC						
AD						

FOREIGN PATENT OR PUBLISHED FOREIGN PATENT APPLICATION

	DOCUMENT NO.	PUBL. DATE	COUNTRY OR PATENT OFFICE	CLASS	SUB CLASS	TRANSLATION YES NO
AI	A 11-330294	11/99	JP			RECEIVED MAY 12 2001
AJ	A 9-64231	03/97	JP			RECEIVED MAY 12 2001
AK	A 5-62980	03/93	JP			RECEIVED MAY 12 2001
AL						
AM						
AN						
AO						
AP						
AQ						

OTHER DOCUMENTS (Including Author, Title, Date, Relevant Pages, Place of Publication)

AT	
AU	
AV	
AX	
AY	

EXAMINER

DATE CONSIDERED

EXAMINER: Initial citation considered. Draw line through citation if not in conformance and not considered.
Include copy of this form with next communication to applicant.